

IN THE CLAIMS

Amend the claims as follows:

1-12. Canceled.

13. (Original) A sensor device implantable in a living body, the sensor device comprising:

an insulating substrate that defines a feedthrough region;

a sensor in contact with the insulating substrate;

an electrical conductor received in the feedthrough region;

a bond wire connected to the electrical conductor and to the sensor,

wherein the bond wire is embedded in an insulative sheath;

a lead connected to the electrical conductor and configured for connection to an implantable medical device; and

wherein the sensor and the substrate are encapsulated in a thin film of hermetic material.

14. (Original) The implantable sensor device as set forth in claim 13 wherein the sensor and the substrate are encapsulated in a layer of insulating material.

15. (Original) The implantable sensor device as set forth in claim 14 wherein the substrate is composed of at least one of ceramic and glass.

16. (Original) The implantable sensor device as set forth in claim 13 wherein the sensor is at least one of a temperature sensor and a pressure sensor.

17. (Original) The implantable sensor device as set forth in claim 13 wherein the hermetic material is at least one of titanium, gold, platinum, and carbon.

18. (Original) The implantable sensor device as set forth in claim 13 wherein the thickness of the thin film of hermetic material is in the range of about 10 nm to 0.1 mm.

19. (Original) The implantable sensor device as set forth in claim 14 wherein the thickness of the layer of insulating material is in the range of about 5.0 nm to 0.5 mm.

20. (Original) The implantable sensor device as set forth in claim 13 and further comprising:
a pad of conductive material intermediate, and in electrical continuity with, the lead and with the electrical conductor.